

TOSHIBA Schottky Barrier Rectifier Schottky Barrier Type

### **CMS06**

## Switching Mode Power Supply Applications Portable Equipment Battery Applications

- Forward voltage:  $V_{FM} = 0.37 \text{ V (max)}$
- Average forward current: If (AV) = 2.0 A
- Repetitive peak reverse voltage:  $V_{RRM} = 30 \text{ V}$
- Suitable for compact assembly due to small surface-mount package "M-FLAT<sup>TM</sup>" (Toshiba package name)

#### Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Repetitive peak reverse voltage	$V_{RRM}$	30	V	
Average forward current	I <sub>F (AV)</sub>	2.0	А	
		(Note)		
Peak one cycle surge forward current	leo.	40 (50 Hz)	Α	
(non-repetitive)	IFSM	40 (30 112)	, A	
Junction temperature	Tj	-40~125	°C	
Storage temperature	T <sub>stg</sub>	-40~150	°C	

Note: T $\ell$  = 82.8°C: Rectangular waveform ( $\alpha$  = 180°C), V<sub>R</sub> = 15 V

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Weight: 0.023 g (typ.)

#### **Electrical Characteristics (Ta = 25°C)**

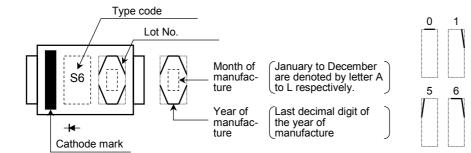
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Peak forward voltage	V <sub>FM (1)</sub>	I <sub>FM</sub> = 0.5 A	_	0.26	_	V
	V <sub>FM (2)</sub>	I <sub>FM</sub> = 1.0 A	_	0.28	_	
	V <sub>FM (3)</sub>	I <sub>FM</sub> = 2.0 A	_	0.32	0.37	
Repetitive peak reverse current	I <sub>RRM</sub>	V <sub>RRM</sub> = 5 V	_	0.09	_	- mA
	I <sub>RRM</sub>	V <sub>RRM</sub> = 30 V	_	1.4	3.0	
Junction capacitance	Cj	V <sub>R</sub> = 10 V, f = 1.0 MHz	_	130	_	pF
Thermal resistance		Device mounted on a ceramic board (soldering land: 2 mm × 2 mm)			60	
	R <sub>th (j-a)</sub>	Device mounted on a glass-epoxy board (soldering land: 6 mm × 6 mm)	_	_	135	°C/W
Thermal resistance	R <sub>th (j-ℓ)</sub>	_	_	_	16	°C/W

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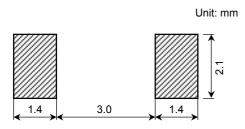
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#### Marking

## Following Indicates the Data of Manufacture

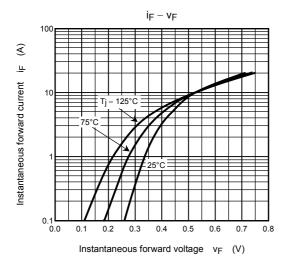


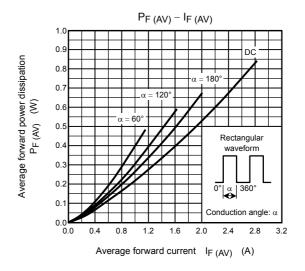
#### **Standard Soldering Pad**

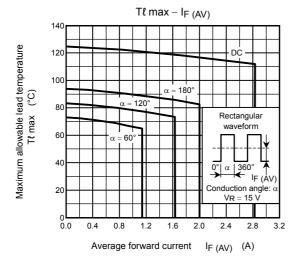


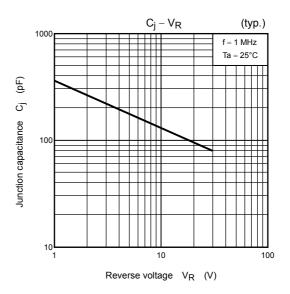
#### **Handling Precaution**

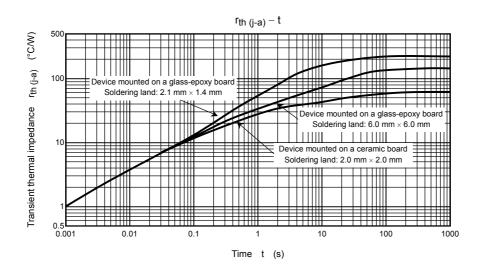
Schottky barrier diodes are having large-reverse-current-leakage characteristic compare to the other rectifier products. This current leakage and improper operating temperature or voltage may cause thermal runaway. Please take forward and reverse loss into consideration when you design.





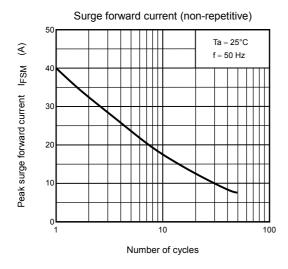


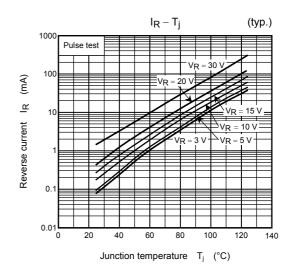


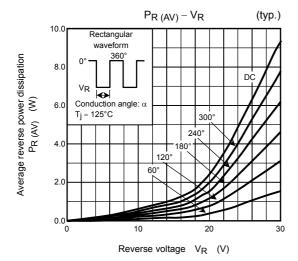


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